

Small Signal Product

300mW, Hermetically Sealed Glass Switching Diodes

FEATURES

- Fast switching device ($t_{rr} < 4.0$ ns)
- Through-hole mount device type
- DO-34 package (JEDEC DO-204)
- Hermetically sealed glass
- Compression bonded construction
- All external surfaces are corrosion resistant and leads are readily solderable
- RoHS compliant
- Solder hot dip Tin (Sn) lead finish
- Cathode indicated by polarity band
- Marking code: 133



DO-34



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	VALUE	UNIT
Power Dissipation	P_D	300	mW
Working Inverse Voltage	W_{IV}	90	V
Average Rectified Current	I_O	150	mA
Non-Repetitive Peak Forward Current	I_{FM}	450	mA
Peak Forward Surge Current	I_{FSURGE}	2	A
Operating Junction Temperature	T_J	+ 175	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-65 to +200	$^\circ\text{C}$

PARAMETER	SYMBOL	MIN	MAX	UNIT
Breakdown Voltage	B_V	80	--	V
Forward Voltage	V_F		1.2	V
Reverse Leakage Current	I_R		500	nA
Junction Capacitance	C_j	--	4.0	pF
Reverse Recovery Time	t_{rr}	--	4.0	ns

Notes: 1. Reverse Recovery Test Conditions: $I_F=I_R=10\text{mA}$, $R_L=100\Omega$, $I_{RR}=1\text{mA}$

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RATINGS AND CHARACTERISTICS CURVES

($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig. 1 Forward Characteristics

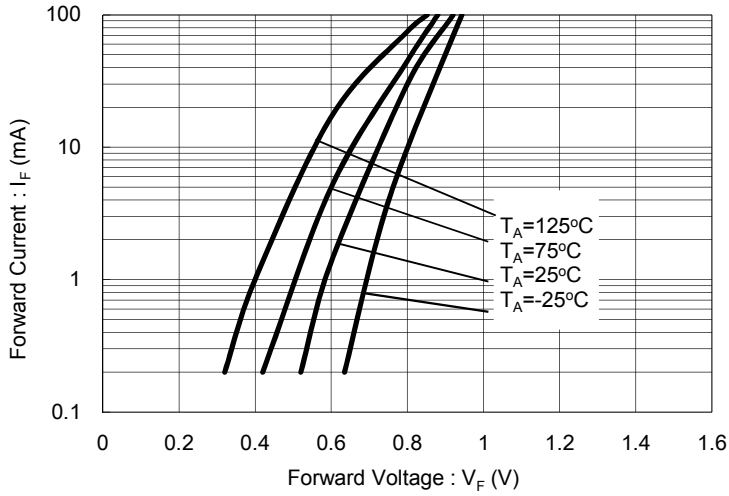


Fig. 2 Reverse Characteristics

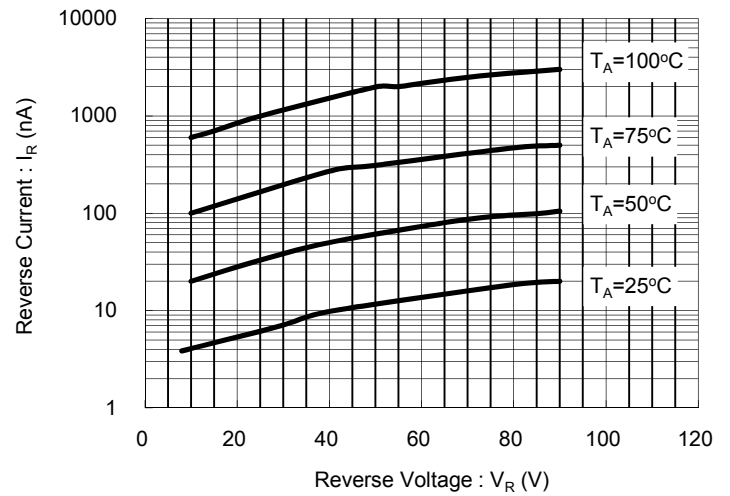


Fig. 3 Capacitance Between Terminals Characteristics

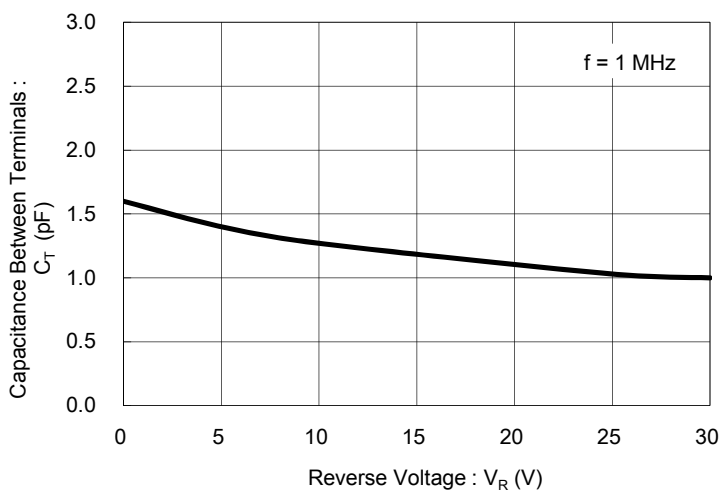


Fig. 4 Reverse Recovery Time Characteristics

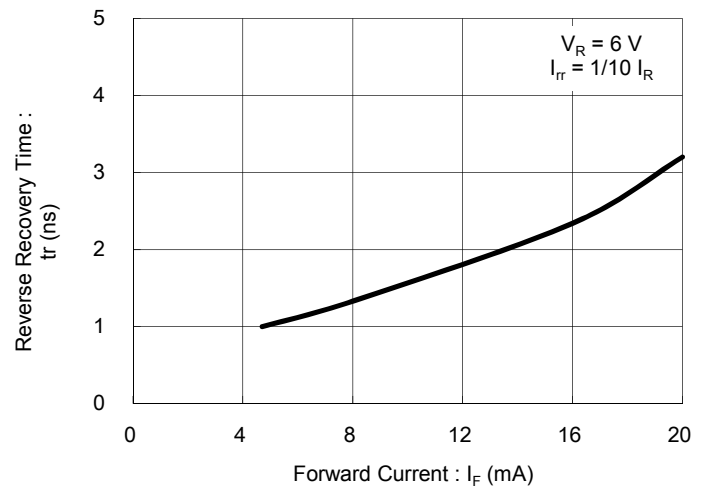


Fig. 5 Surge Current Characteristics

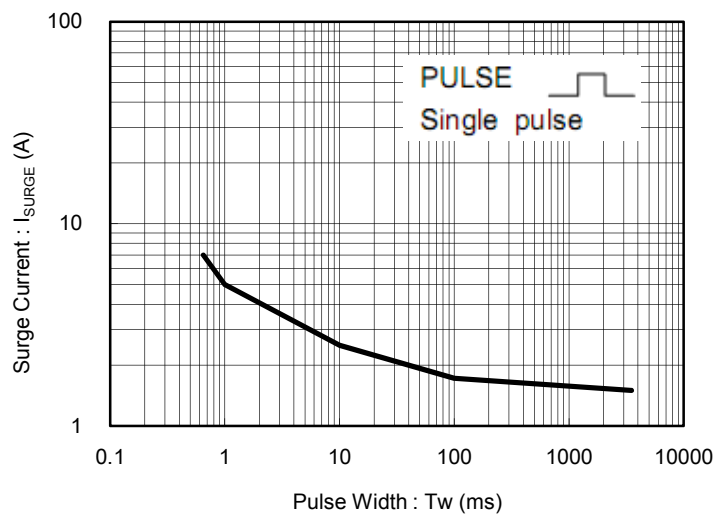
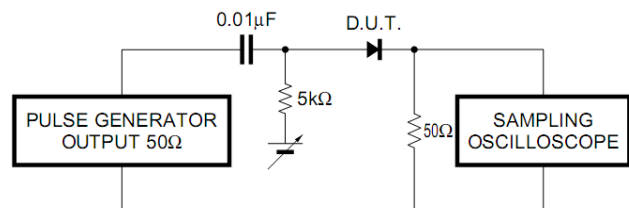


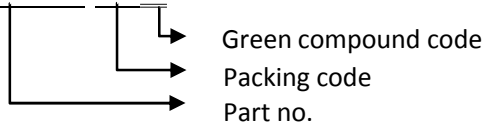
Fig. 6 Reverse Recovery Time (t_r) Measurement Circuit



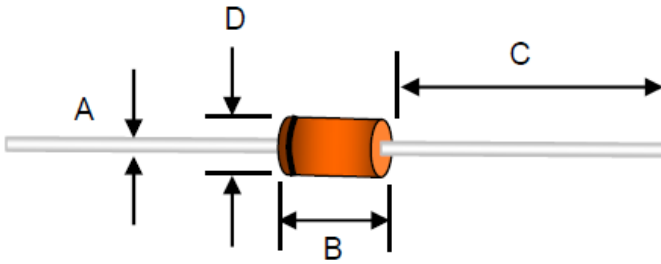
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ORDER INFORMATION (EXAMPLE)

1SS133M R0G



PACKAGE OUTLINE DIMENSIONS



DIM.	Unit(mm)		Unit(inch)	
	Min	Max	Min	Max
A	0.30	0.55	0.012	0.022
B	2.16	3.04	0.085	0.120
C	25.40	38.10	1.000	1.500
D	1.27	2.00	0.050	0.079